

Extraction Tool 58113-[]

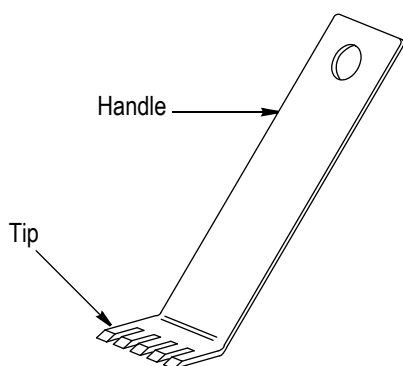
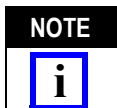


Figure 1

1. INTRODUCTION

Extraction Tool 58113-[] is used to extract a pin grid array (PGA) substrate package (device) from a low insertion force (LIF) PGA socket installed onto a printed circuit (pc) board. Read these instructions thoroughly before extracting any devices.



Dimensions in this instruction sheet are in millimeters [with inches in brackets]. Figures are not drawn to scale.

Reasons for reissue of this instruction sheet are provided in Section 6, REVISION SUMMARY.

2. DESCRIPTION

Each tool features a handle and a tip with blades. See Figure 1.

3. USING THE TOOL (Refer to Figure 2)



Make sure that all power to the system is "OFF" before using the tool.

1. Insert the tip of the extraction tool (with the end of the handle above the socket) between the device and socket, then gently lift the handle until that side of the device is raised from the socket.

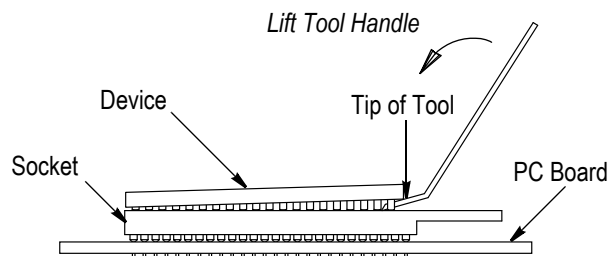


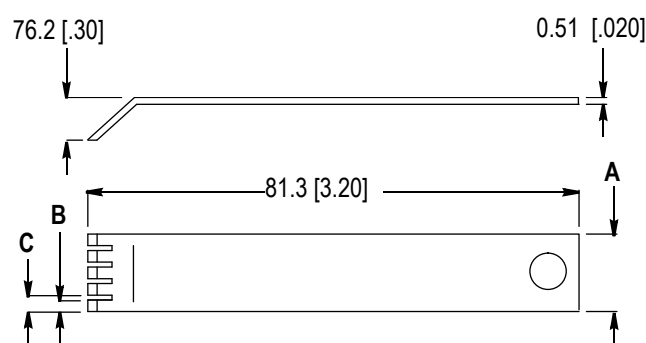
Figure 2

2. Remove the extraction tool, then insert the tip (as previously described) into the opposite side of the assembly, then gently lift the handle until that side of the device is raised from the socket.

3. Repeat this process for the remaining sides of the assembly until the device is released from the socket.

4. TOOL INSPECTION

Inspect the tool immediately upon arrival and at regularly scheduled intervals according to Figure 3 to ensure that the tool is not damaged.



TOOL	NUMBER OF BLADES	DIMENSION		
		A	B Typ	C Typ
58113-1	5	11.7 [.46]	1.52 [.060]	2.54 [.100]
58113-3	10	24.4 [.96]		
58113-4	13	32.0 [1.26]		
58113-5	16	39.6 [1.56]		

Figure 3

5. REPLACEMENT

The extraction tool cannot be repaired. Order replacement tools through your representative, or call 1-800-526-5142, or send a facsimile of your purchase order to 717-986-7605, or write to:

CUSTOMER SERVICE (038-035)
 TYCO ELECTRONICS CORPORATION
 PO BOX 3608
 HARRISBURG PA 17105-3608

6. REVISION SUMMARY

Revisions to this instruction sheet include:

- Updated instruction sheet to corporate requirements